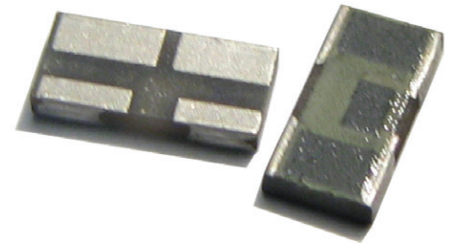


Surface Mount Thick Film Attenuator on AlN

Thick Film

V-Series Dimensions			Power Rating			
Part Number	Length x Width	Height	5dB ΔT of 50°C	5dB ΔT of 100°C	20dB ΔT of 50°C	20dB ΔT of 100°C
VGX-2010	0.197" x 0.097"	0.035" Max.	45W	90W	35W	70W
VGX-3725	0.375" x 0.250"	0.035" Max.	175W	350W	180W	360W
VDX-2010	0.197" x 0.097"	0.025" Max.	80W	155W	60W	120W
VDX-3725	0.375" x 0.250"	0.025" Max.	290W	590W	300W	600W

Item	Specification
Value Range:	0dB, 1dB to 30dB
Standard Impedance:	50Ω Nominal
VSWR (Max)-G 0.025	2010 - 1.4:1 up to 7GHz ² 3725 - 1.6:1 up to 4.5GHz ²
VSWR (Max)-D 0.015	*2010 - 1.4:1 up to 5GHz ² *3725 - 1.6:1 up to 1.5GHz ² <small>*Simulated (pending final test)</small>
DC Attenuation Stability:	.001 dB/ dB/ deg. C ³
Operating Temperature:	-55 deg. C to 150 deg. C
Nominal Thermal Resistance: ⁴	~2.5°C/W (2010), ~0.6°C/W (3725)
Architecture:	Thick Film on Aluminum Nitride
Attachment:	Solder and Epoxy



For other impedances, values, substrate thicknesses, sizes or power levels, consult the factory.

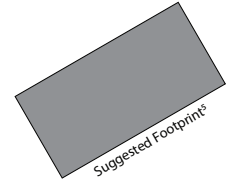
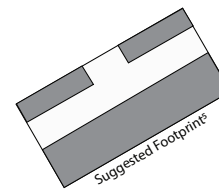
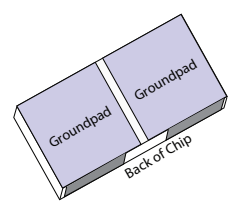
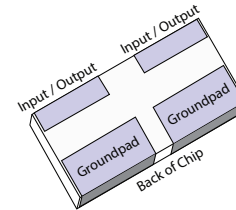
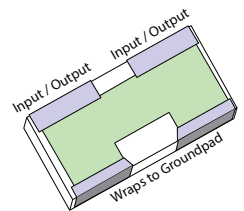
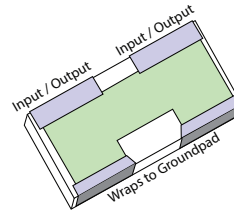
Attenuation Accuracy

Increment (dB)	Accuracy
1, 1 -3	+/- 0.2dB
3.5 - 13	+/- 0.3dB
13.5 - 30	+/- 0.5dB



WA Style

SG Style



Ordering Information

V G 3 - 2010 WA 02D0

<p>Prefix for AlN attenuators</p> <p>Substrate Thickness</p> <p>D - 0.015"</p> <p>G - 0.025"</p> <p>Termination Metallization</p> <p><input checked="" type="checkbox"/> 3 PtAg</p> <p><input checked="" type="checkbox"/> 8 ULR PtAg</p> <p>C PtAg with Sn62 solder</p> <p>H ULR PtAg with Sn62 solder</p> <p><input checked="" type="checkbox"/> R ULR PtAg with Sn96 solder</p> <p>Case Size</p> <p>2010 3725</p>	<p>dB Value</p> <p>ex: 03D5=3.5dB</p> <p>Half dB available</p> <p>1-17 dB range</p> <p>ex: 14D0=14.0dB</p> <p>Whole dB available</p> <p>0-30dB range</p> <p>Termination Style</p> <p>WA - Wraparound</p> <p>SG - Single Wrap to Ground</p> <p style="text-align: right;"><input checked="" type="checkbox"/> Indicates RoHS Compliance</p>
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1 Baseplate maintained at or below 100°C
 2 Mounted in a matched continuous, 50Ω microstrip system
 3 Based on TCR and resistor tolerance at DC

4 Based on a max power, max film temp. of 150°C and baseplate temp. of 100°C
 5 Groundpads must be shorted during assembly